

Product Change Notification

(Notification - P1808047c-DIGI)

(CST-R2-AJ129/130 / DCY001)

August 17, 2018

To: *Our Valued Digi-Key Electronics Customer*

Overview: The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices.

This notification announces the change in assembly site and materials for select SRAM products. There is a part number change. There is no change to electrical specifications or product reliability.

One or more of following items will change (please see the Appendix for specific details).

1. Assembly site from Renesas Semiconductor (Beijing, China) to Greatek Electronics Inc. (Taiwan)
2. Base Metal of Lead Frame from 42Alloy to Cu
3. Lead Plating from Sn-Cu to Cu
4. Die thickness
5. Magazine (Tube) specification, or Tape and Reel specification
6. Inner lead pattern
7. Moisture Sensitivity Level from MSL2 to MSL3
8. Topmark specification
9. Molding compound to halogen free
10. Die bonding from epoxy film to epoxy paste

Affected Products: A review of our records indicates the products listed in Appendix 1 may affect your company.

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Final last time buy (LTB) orders placed to REA or to a franchised REA distributor.	June 15th, 2019
Planned date for last time shipment (LTS) from REA.	Dec. 15th, 2019
Replacement parts samples	Mar. 2019
Replacement parts mass production	June 2019

Response: Please place last time buy (LTB) orders in a timely manner prior to the key dates listed to avoid product availability issues. If you anticipate volumes beyond your regular rate, please contact your REA sales representative with a forecast of your requirements. Shipments between the LTB and LTS dates are Non-Cancelable and Non-Returnable (NCNR).

Please work with your REA sales representative and/or FAE to transition to the replacement devices.

Please contact your REA sales representative for any questions or comments.

Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

Appendix 1: Affected Part Numbers and Replacements for Digi-Key

Booking Part Number	Replacement PN
R1RP0408DGE-2LR#B0	R1RP0408DGE-2LR#B1
R1RP0408DGE-2PI#B0	R1RP0408DGE-2PI#B1
R1RP0408DGE-2PR#B0	R1RP0408DGE-2PR#B1
R1RP0416DGE-2LR#B0	R1RP0416DGE-2LR#B1
R1RP0416DGE-2PI#B0	R1RP0416DGE-2PI#B1
R1RP0416DGE-2PR#B0	R1RP0416DGE-2PR#B1
R1RW0408DGE-2LR#B0	R1RW0408DGE-2LR#B1
R1RW0408DGE-2PI#B0	R1RW0408DGE-2PI#B1
R1RW0408DGE-2PR#B0	R1RW0408DGE-2PR#B1
R1RW0416DGE-2PI#B0	R1RW0416DGE-2PI#B1
R1RW0416DGE-2PR#B0	R1RW0416DGE-2PR#B1
RMLV0816BGSD-4S2#AC0	RMLV0816BGSD-4S2#AA1
RMLV0816BGSD-4S2#HC0	RMLV0816BGSD-4S2#HA1
RMLV1616AGSD-5S2#AC0	RMLV1616AGSD-5S2#AA1
RMLV1616AGSD-5S2#HC0	RMLV1616AGSD-5S2#HA1

Appendix 2: Change Details [52pin- μ TSOP 8Mb(3V), Part Name: RMLV0816BGSD-4S2]

Item		Pre change (EOL product)	Post change (Successor product)
Orderable part name		RMLV0816BGSD-4S2#AC0 (Tray packing)	RMLV0816BGSD-4S2#AA1 (Tray packing)
		RMLV0816BGSD-4S2#HC0 (Tape & Reel packing)	RMLV0816BGSD-4S2#HA1 (Tape & Reel packing)
Assembly line		Renesas Semiconductor Beijing (China)	Gretek Electronics Inc. (Taiwan)
JEITA Package Code		P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification			
Assembly Material	Lead frame material	42Alloy	Cu
	Inner lead pattern	Current pattern	Changed
	Outer lead pattern	Current pattern	Unchanged
	Lead plating	Sn-Cu	Sn (pure tin)
	Die bonding	Epoxy film	Epoxy paste
	Wire bonding	Au	Au
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)
Die thickness		Current thickness	Changed
Final test line		Powertech Technology Inc. (Taiwan)	←
Tray packing	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-24)	←
	Storage number	230pcs/tray	←
	Number of trays (Max.)	10 trays + 1 tray (cover)	←
	Inner box size (LxWxH)	351mm x 175mm x 104mm	←
Tape & Reel packing	Embossed tape	Current specification	New specification
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	289mm x 264mm x 60mm	←
Moisture-proof performance		MSL 2	MSL 3
Shipping label		Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)

Appendix 3: Change Details [52pin-μTSOP 16Mb(3V), Part Name: RMLV1616AGSD-5S2]

Item		Pre change (EOL product)	Post change (Successor product)
Orderable part name		RMLV1616AGSD-5S2#AC0 (Tray packing)	RMLV1616AGSD-5S2#AA1 (Tray packing)
		RMLV1616AGSD-5S2#HC0 (Tape & Reel packing)	RMLV1616AGSD-5S2#HA1 (Tape & Reel packing)
Assembly line		Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)
JEITA Package Code		P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification			
Assembly Material	Lead frame material	42Alloy	Cu
	Inner lead pattern	Current pattern	Changed
	Outer lead pattern	Current pattern	Unchanged
	Lead plating	Sn-Cu	Sn (pure tin)
	Die bonding	Epoxy film	Epoxy paste
	Wire bonding	Au	Au
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)
Die thickness		Current thickness	Changed
Final test line		Powertech Technology Inc. (Taiwan)	←
Tray packing	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-24)	←
	Storage number	230pcs/tray	←
	Number of trays (Max.)	10 trays + 1 tray (cover)	←
	Inner box size (LxWxH)	351mm x 175mm x 104mm	←
Tape & Reel packing	Embossed tape	Current specification	New specification
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	289mm x 264mm x 60mm	←
Moisture-proof performance		MSL 2	MSL 3
Shipping label		Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)

Appendix 4: Change Details [36pin-SOJ 4Mb Fast(5V) x8, Part Name: R1RP0408DGE-*]**

Item		Pre change (EOL product)	Post change (Successor product)
Orderable part name		R1RP0408DGE-2LR/-2PI/-2PR#B0 (Magazine packing)	R1RP0408DGE-2LR/-2PI/-2PR#B1 (Magazine packing)
Assembly line		Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)
Country of origin display		CHINA	TAIWAN
JEITA Package Code		P-SOJ36-10.16x23.39-1.27	←
Package marking specification (The Electrical characteristics is an example.)			
Assembly Material	Lead frame material	42Alloy	Cu
	Inner lead pattern	Current pattern	Changed
	Outer lead pattern	Current pattern	Unchanged
	Lead plating	Sn-Cu	Sn (pure tin)
	Die bonding	Epoxy film	Epoxy paste
	Wire bonding	Au	Au
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)
Die thickness		Current thickness	Changed
Final test line		Powertech Technology Inc. (Taiwan)	←
Magazine packing	Magazine	Magazine code : JP400PC	New specification
	Storage number	22pcs/magazine	←
	Number of magazines (Max.)	60 magazines	←
	Inner box size (LxWxH)	595mm x 170mm x 72mm	←
Moisture-proof performance		MSL 2	MSL 3
Shipping label		Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)

Appendix 5: Change Details [36pin-SOJ 4Mb Fast(3V) x8, Part Name: R1RW0408DGE-*]**

Item		Pre change (EOL product)	Post change (Successor product)
Orderable part name		R1RW0408DGE-2LR/-2PI/-2PR#B0 (Magazine packing)	R1RW0408DGE-2LR/-2PI/-2PR#B1 (Magazine packing)
Assembly line		Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)
Country of origin display		CHINA	TAIWAN
JEITA Package Code		P-SOJ36-10.16x23.39-1.27	←
Package marking specification (The Electrical characteristics is an example.)			
Assembly Material	Lead frame material	42Alloy	Cu
	Inner lead pattern	Current pattern	Changed
	Outer lead pattern	Current pattern	Unchanged
	Lead plating	Sn-Cu	Sn (pure tin)
	Die bonding	Epoxy film	Epoxy paste
	Wire bonding	Au	Au
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)
Die thickness		Current thickness	Changed
Final test line		Powertech Technology Inc. (Taiwan)	←
Magazine packing	Magazine	Magazine code : JP400PC	New specification
	Storage number	22pcs/magazine	←
	Number of magazines (Max.)	60 magazines	←
	Inner box size (LxWxH)	595mm x 170mm x 72mm	←
Moisture-proof performance		MSL 2	MSL 3
Shipping label		Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)

Appendix 6: Change Details [44pin-SOJ 4Mb Fast(5V) x16, Part Name: R1RP0416DGE-*]**

Item		Pre change (EOL product)	Post change (Successor product)
Orderable part name		R1RP0416DGE -2LR/-2PI/-2PR/-2SR/-2UR/-2VR#B0 (Magazine packing) -2LR/-2PR#BN (Magazine packing)	R1RP0416DGE -2LR/-2PI/-2PR/-2SR/-2UR/-2VR#B1 (Magazine packing)
Assembly line		Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)
Country of origin display		CHINA	TAIWAN
JEITA Package Code		P-SOJ44-10.16x28.47-1.27	←
Package marking specification (The Electrical characteristics is an example.)			
Assembly Material	Lead frame material	42Alloy	Cu
	Inner lead pattern	Current pattern	Changed
	Outer lead pattern	Current pattern	Unchanged
	Lead plating	Sn-Cu	Sn (pure tin)
	Die bonding	Epoxy film	Epoxy paste
	Wire bonding	Au	Au
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)
Die thickness		Current thickness	Changed
Final test line		Powertech Technology Inc. (Taiwan)	←
Magazine packing	Magazine	Magazine code : JP400PC	New specification
	Storage number	18pcs/magazine	←
	Number of magazines (Max.)	60 magazines	←
	Inner box size (LxWxH)	595mm x 170mm x 72mm	←
Moisture-proof performance		MSL 2	MSL 3
Shipping label		Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)

Appendix 7: Change Details [44pin-SOJ 4Mb Fast(3V) x16 Part name: R1RW0416DGE-*]**

Item		Pre change (EOL product)	Post change (Successor product)
Orderable part name		R1RW0416DGE-2LR/-2PI/-2PR#B0 (Magazine packing)	R1RW0416DGE-2LR/-2PI/-2PR#B1 (Magazine packing)
Assembly line		Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)
Country of origin display		CHINA	TAIWAN
JEITA Package Code		P-SOJ44-10.16x28.47-1.27	←
Package marking specification (The Electrical characteristics is an example.)			
Assembly Material	Lead frame material	42Alloy	Cu
	Inner lead pattern	Current pattern	Changed
	Outer lead pattern	Current pattern	Unchanged
	Lead plating	Sn-Cu	Sn (pure tin)
	Die bonding	Epoxy film	Epoxy paste
	Wire bonding	Au	Au
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)
Die thickness		Current thickness	Changed
Final test line		Powertech Technology Inc. (Taiwan)	←
Magazine packing	Magazine	Magazine code : JP400PC	New specification
	Storage number	18pcs/magazine	←
	Number of magazines (Max.)	60 magazines	←
	Inner box size (LxWxH)	595mm x 170mm x 72mm	←
Moisture-proof performance		MSL 2	MSL 3
Shipping label		Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)

Appendix 8: Magazine (Tube) Specification Change

- a. The cross-sectional shape of magazine is to be changed (see below).
- b. No change in the length of magazine (L=550mm).

	Pre Change (EOL product)	Post Change (Successor product)
36pin-SOJ 44pin-SOJ (Unit:mm)		

Appendix 8: Tape & Reel Specification Change

- a. The package seat position in taping pocket is to be change (see below).
- b. No change in width and pitch of embossed carrier tape.
- c. No change in reel diameter.

Package type	Pre Change (EOL product)		Post Change (Successor product)
	Emboss type name	PKG seat position (mm)	PKG seat position (mm)
52pin-μTSOP	MTE2416H-52PTG-A	1.3	2.5



Cross section of taping pocket